



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10C101GB8NNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 100pF, 50V, ±2%, C0G, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>C</u> <u>101</u> <u>G</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

| 1   | Series        | Samsung Multi-layer Ceramic Capacitor |                 |                         |  |
|-----|---------------|---------------------------------------|-----------------|-------------------------|--|
| 2   | Size          | 0603 (inch code)                      | L: 1.6 ± 0.1 mm | W: 0.8 ± 0.1 mm         |  |
| (3) | Dielectric    | C0G                                   | Inner electrode | Ni                      |  |
| _   |               |                                       | 9               | _                       |  |
| 4   | Capacitance   | <b>100</b> pF                         | Termination     | Cu                      |  |
| (5) | Capacitance   | ±2 %                                  | Plating         | Sn 100% (Pb Free)       |  |
|     | tolerance     |                                       | Product         | Normal                  |  |
| 6   | Rated Voltage | 50 V                                  | Special         | Reserved for future use |  |
| 7   | Thickness     | 0.8 ± 0.1 mm                          | Packaging       | Cardboard Type, 7" reel |  |

## **B. Samsung Reliability Test and Judgement condition**

|                                    | Performance  | Test condition                         |  |
|------------------------------------|--|--|--|
| Capacitance                        | Within specified tolerance   | 1Mb±10% 0.5~5Vrms                      |  |
| Q                                  | 1000 min   |  |  |
| Insulation                         | 10,000Mohm or 500Mohm⋅ <i>μ</i> F                                    | Rated Voltage 60~120 sec.              |  |
| Resistance                         | Whichever is Smaller   |  |  |
| Appearance                         | No abnormal exterior appearance                                      | Microscope (×10)                       |  |
| Withstanding                       | No dielectric breakdown or   | 300% of the rated voltage              |  |
| Voltage mechanical breakdown       |  |  |  |
| Temperature C0G                    |  |  |  |
| Characteristics                    | (From -55 ℃ to 125 ℃, Capacitance change should be within ±30PPM/ ℃) |  |  |
| Adhesive Strength                  | No peeling shall be occur on the                                     | 500g·F, for 10±1 sec.                  |  |
| of Termination                     | terminal electrode   |  |  |
| Bending Strength                   | Capacitance change :   | Bending to the limit (1mm)             |  |
|                                    | within ±5% or ±0.5pF whichever is larger                             | with 1.0mm/sec.                        |  |
| Solderability                      | More than 75% of terminal surface                                    | SnAg3.0Cu0.5 solder                    |  |
|                                    | is to be soldered newly  | 245±5°C, 3±0.3sec.                     |  |
|                                    |  | (preheating : 80~120 °C for 10~30sec.) |  |
|                                    |  |  |  |
| Resistance to Capacitance change : |  | Solder pot : 270±5℃, 10±1sec.          |  |
| Soldering heat                     | within ±2.5% or ±0.25pF whichever is larger                          |  |  |
|                                    | Tan δ, IR : initial spec.  |  |  |

|                  | Performance                                 | Test condition                      |  |
|------------------|---|-------------------------------------|--|
| Vibration Test   | Capacitance change :                        | Amplitude : 1.5mm                   |  |
|                  | within ±2.5% or ±0.25pF whichever is larger | From 10Hz to 55Hz (return : 1min.)  |  |
|                  | Tan δ, IR : initial spec.                   | 2hours × 3 direction (x, y, z)      |  |
| Moisture         | Capacitance change :                        | With rated voltage                  |  |
| Resistance       | within ±7.5% or ±0.75pF whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs       |  |
|                  | Q: 200 min                                  |                                     |  |
|                  | IR : 500Mohm or 25Mohm $\cdot \mu$ F        |                                     |  |
|                  | Whichever is Smaller                        |                                     |  |
| High Temperature | Capacitance change :                        | With 200% of the rated voltage      |  |
| Resistance       | within ±3% or ±0.3pF whichever is larger    | Max. operating temperature          |  |
|                  | Q: 350 min                                  | 1000+48/-0hrs                       |  |
|                  | IR : 1000Mohm or 50Mohm $\cdot \mu$ F       |                                     |  |
|                  | Whichever is Smaller                        |                                     |  |
| Temperature      | Capacitance change :                        | 1 cycle condition                   |  |
| Cycling          | within ±2.5% or ±0.25pF whichever is larger | Min. operating temperature → 25°C   |  |
|                  | Tan δ, IR : initial spec.                   | → Max. operating temperature → 25°C |  |
|                  |   |                                     |  |
|                  |   |                                     |  |
|                  |   | 5 cycle test                        |  |

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C , 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.